



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2014-06-20
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Antonella Lanzafame	Representative Title	AMS Materials Declaration Champion)
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
SG3524P013TR	KKQ7*L750UA6	A	SH1A	2019-04-23
Amount	UoM	Unit type	ST ECOPACK Grade	
150.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	3.9,9.9,1.25	16	gull wing	
Comment	SO 16 .15 TO JEDEC MS-012			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

#REF!				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	KKQ7*L750U46						
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)	
die (s)	Other inorganic materials	2.912	mg	supplier	die	Silicon (Si)	7440-21-3		2.844	mg	976648	18960	
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.036	mg	12363	240	
die (s)				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.012	mg	4121	80	
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.017	mg	5838	113	
die (s)				supplier	back side metallization	Gold (Au)	7440-57-5		0.001	mg	343	7	
die (s)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.002	mg	687	13	
Leadframe	Copper & its alloys	31.952	mg	supplier	alloy	Copper (Cu)	7440-50-8		31.012	mg	970581	206747	
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.729	mg	22815	4860	
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.044	mg	1377	293	
Leadframe				supplier	alloy	Zinc (Zn)	7440-66-6		0.038	mg	1189	253	
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.117	mg	3662	780	
Leadframe				supplier	metallization	Palladium (Pd)	7440-05-3		0.004	mg	125	27	
Leadframe				supplier	metallization	Gold (Au)	7440-57-5		0.004	mg	125	27	
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		0.004	mg	125	27	
Die attach	Other inorganic materials	0.334	mg	supplier	glue or tape	Silver (Ag)	7440-22-4		0.167	mg	500000	1113	
Die attach				supplier	glue or tape	Aluminium (Al)	7429-90-5		0.117	mg	350299	780	
Die attach				supplier	glue or tape	acrylic resin	Proprietary		0.017	mg	50898	113	
Die attach				supplier	glue or tape	Ethylene glycol dicyclopentyl ether acrylate	65983-31-5		0.027	mg	80838	180	
Die attach				supplier	glue or tape	[3-(2,3-epoxypropoxy)propyl] trimethoxysilane	2530-83-8		0.003	mg	8982	20	
Die attach				supplier	glue or tape	Butadiene copolymer	68891-50-9		0.003	mg	8982	20	
Bonding wire				supplier	wire	Copper (Cu)	7440-50-8		0.109	mg	1000000	727	
encapsulation	Other Organic Materials	114.693	mg	supplier	mold compound	Silica, vitreous	60676-86-0		100.286	mg	874386	668573	
encapsulation				supplier	mold compound	Epoxy resin A	EC 413-900-7		4.574	mg	39880	30493	
encapsulation				supplier	mold compound	Epoxy resin B	29690-82-2		4.574	mg	39880	30493	
encapsulation				supplier	mold compound	phenol resin	Proprietary		3.43	mg	29906	22867	
encapsulation				supplier	mold compound	carbon black	1333-86-4		0.343	mg	2991	2287	
encapsulation				supplier	mold compound	carbon black	1333-86-4		0.343	mg	2991	2287	
encapsulation				supplier	mold compound	additive	Proprietary		1.143	mg	9966	7620	